REMARKS

Claims 17-23 are pending in this response.

I. Specification Objection:

The Examiner objected to "polyimide" being misspelled as "polyimid." This misspelling has been addressed by amendment where it appears on page 9 and in the Abstract.

II. Rejections Over the Prior Art:

The Examiner continues to focus on the nature of the material used for the substrate, and notes that the prior art seems to disclose materials for the substrate similar to those disclosed by the Applicant, which may or may not change conductivity after curing. As a result, the Examiner suggests that it is the Applicant's duty to prove that the materials in the prior art references (i.e., USP 5,364,707 ("Swisher"); USP 4,368,281 ("Brummett"); or 5,130,192 ("Takabayashi")) do not undergo conductivity changes when eventually cured.

But in focusing on whether such materials undergo a conductivity change, the Examiner overlooks an aspect of what Applicant claims, which Applicant has tried to make clearer in this response by amendment. Specifically, ***Applicant claims an intermediary structure comprising (inter alia) a substrate comprising an uncured material with at least one metal trace thereon***:

> 17. An intermediate structure formed during the manufacture of a printed circuit board, comprising:
>
> a substrate comprised of a material having a first conductivity, wherein the substrate material is uncured;
>
> at least one metal trace formed on the uncured substrate; and
>
> an electrolytic plating layer coated on at least a portion of the at least one metal trace.

When this claimed aspect is recognized, it becomes unimportant whether the substrate materials of the prior art do or do not change conductivity upon curing. ***The fact remains that none of the prior art references disclose a substrate comprising an uncured material with at least one metal trace formed thereon.*** Instead, one of skill in the art would understand the cited references to disclose what is ***traditional*** concerning the formation of printed circuit boards:

namely, that ***the substrate material is cured, and then the metal trace(s) is/are formed thereon***. Nothing in the cited references discloses or suggests that any metal traces are applied to the substrate materials in those references prior to curing of the substrate material. Accordingly, none of the cited references can anticipate or render obvious Applicant's claims.

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Based on the above remarks, Applicant respectfully submits that pending claims 17-23 are allowable, and requests that a Notice of Allowance issue for these claims.

Respectfully submitted,

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